

ABSTRACT

An interconnect for use with a pixel layer of a pixel web is provided, the interconnect including an interconnect substrate having a plurality of conductive leads and a plurality of contact vias formed on and extending from the interconnect substrate. The contact vias are formed in a predetermined pattern on the interconnect substrate and are in electrical communication with the conductive leads. The interconnect includes a patterned spacer of a thickness substantially equal to a height of the contact vias. The patterned spacer includes a plurality of through-holes also formed according to the predetermined pattern and having a dimension substantially equal to a dimension of the contact vias. The interconnect substrate and the patterned spacer are capable of being assembled onto the pixel layer, with the patterned spacer being in a middle position and the contact vias extending through the through-holes to contact corresponding cathode portions on the pixel layer.